

# Initial Product/Process Change Notification

Document #:IPCN23267X Issue Date:15 Apr 2020

| Title of Change:                          | SPM32 direct bonding copper (DBC) substrate pattern change.  |                               |  |
|---|--|-------------------------------|--|
| Proposed First Ship date:                 | 15 Oct 2020 or earlier if approved by customer   |                               |  |
| Contact Information:                      | Contact your local ON Semiconductor Sales Office or <a href="Daisy.Zhi@onsemi.com">Daisy.Zhi@onsemi.com</a>  |                               |  |
| PCN Samples Contact:                      | Contact your local ON Semiconductor Sales Office or <a href="PCN.samples@onsemi.com">PCN.samples@onsemi.com</a> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.  |                               |  |
| Type of Notification:                     | This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <a href="mailto:PCN.Support@onsemi.com">PCN.Support@onsemi.com</a> |                               |  |
| Marking of Parts/ Traceability of Change: | No Marking change and date code to traceability  |                               |  |
| Change Category:                          | Assembly Change  |                               |  |
| Change Sub-Category(s):                   | Material Change  |                               |  |
| Sites Affected:                           |  |                               |  |
| ON Semiconductor Sites                    |  | External Foundry/Subcon Sites |  |
| ON Semiconductor Suzhou, China            |  | None                          |  |
|   |  |                               |  |

### **Description and Purpose:**

DBC left bottom corner shape is rectangle in current and will change to etched in the future.

|                    | Before Change Description                 | After Change Description               |  |
|--------------------|---|--|--|
|                    | DBC left bottom corner shape is rectangle | DBC left bottom corner shape is etched |  |
|                    |   | 1 1                                    |  |
| DBC pattern change |   |  |  |

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#### **Qualification Plan:**

**QV DEVICE NAME:** FSAM75SM60A

**RMS** : <u>U62238</u> **PACKAGE** : <u>SPM32</u>

| Test  | Specification | Condition                                       | Interval       |
|-------|---------------|---|----------------|
| HTSL  | JESD22-A103   | Ta= <u>125</u> °C                               | _1008 hrs      |
| TC    | JESD22-A104   | Ta=- <u>40</u> °C to + <u>125</u> °C            | _1000 cyc      |
| H3TRB | JESD22-A101   | 85°C, RH=85%, bias = 80% of rated V or 100V max | _1008 hrs      |
| uHAST | JESD22-A118   | 110°C, 85% RH, 18.8psig, unbiased               | <u>264</u> hrs |
| RSH   | JESD22- B106  | Ta = 265C, 10 sec                               |                |

### **List of Affected Parts:**

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.

| Part Number  | Qualification Vehicle |
|--------------|-----------------------|
| FSAM75SM60A  | FSAM75SM60A           |
| FSAM75SM60SL | FSAM75SM60A           |

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